

# SOT630-2

plastic thin fine-pitch ball grid array package; 112 balls; body  
7 x 7 x 0.7 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	TFBGA112
<b>Package type industry code</b>	TFBGA112
<b>Package style descriptive code</b>	TFBGA (thin fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-195
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	27-4-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	[tbd]	-	1.1	1.1	mm
A <sub>2</sub>	package height	0.65	-	0.7	0.8	mm
n <sub>2</sub>	actual quantity of termination	-	-	112	-	



## 2. Package outline

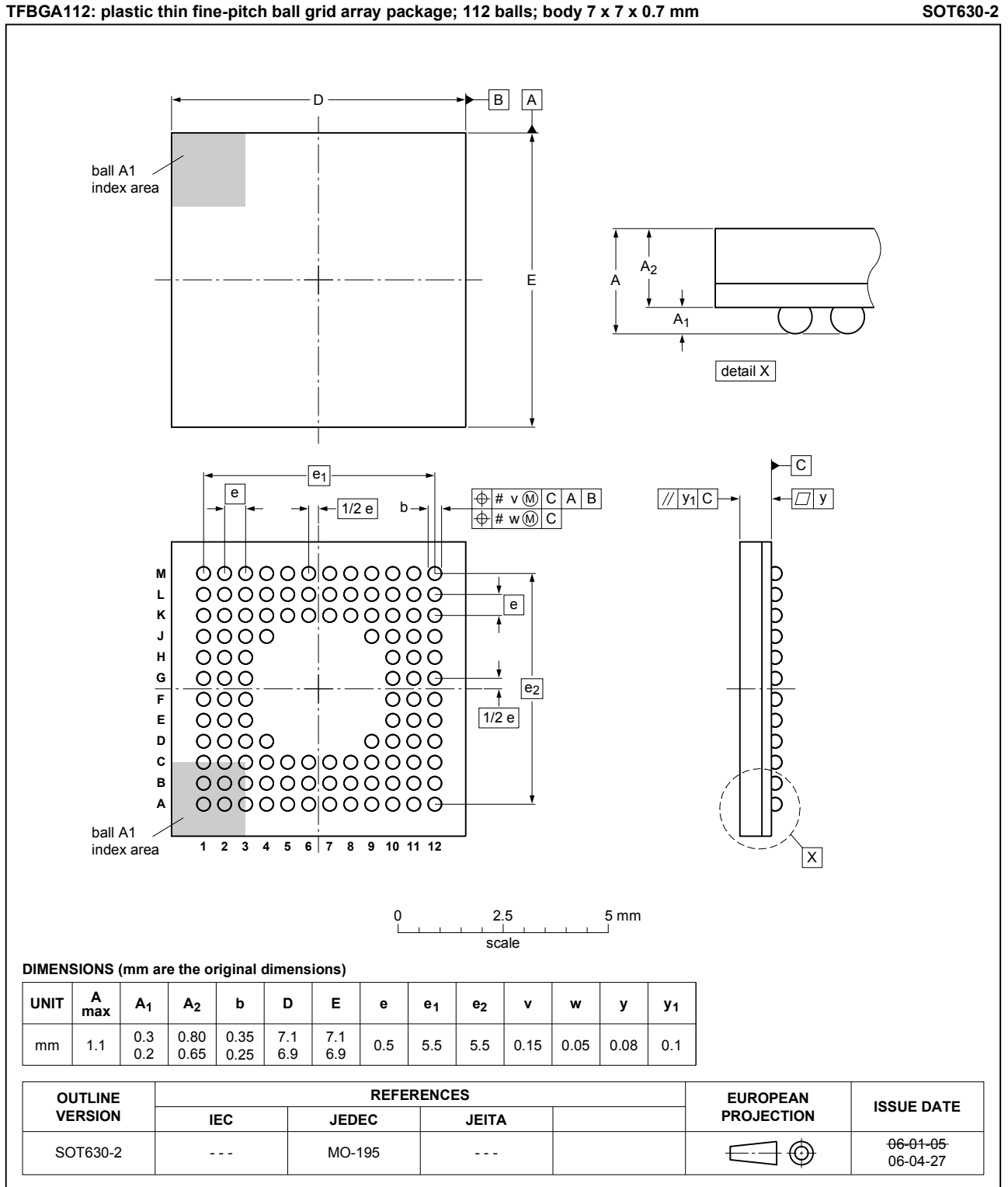


Fig. 1. Package outline TFBGA112 (SOT630-2)

### 3. Soldering

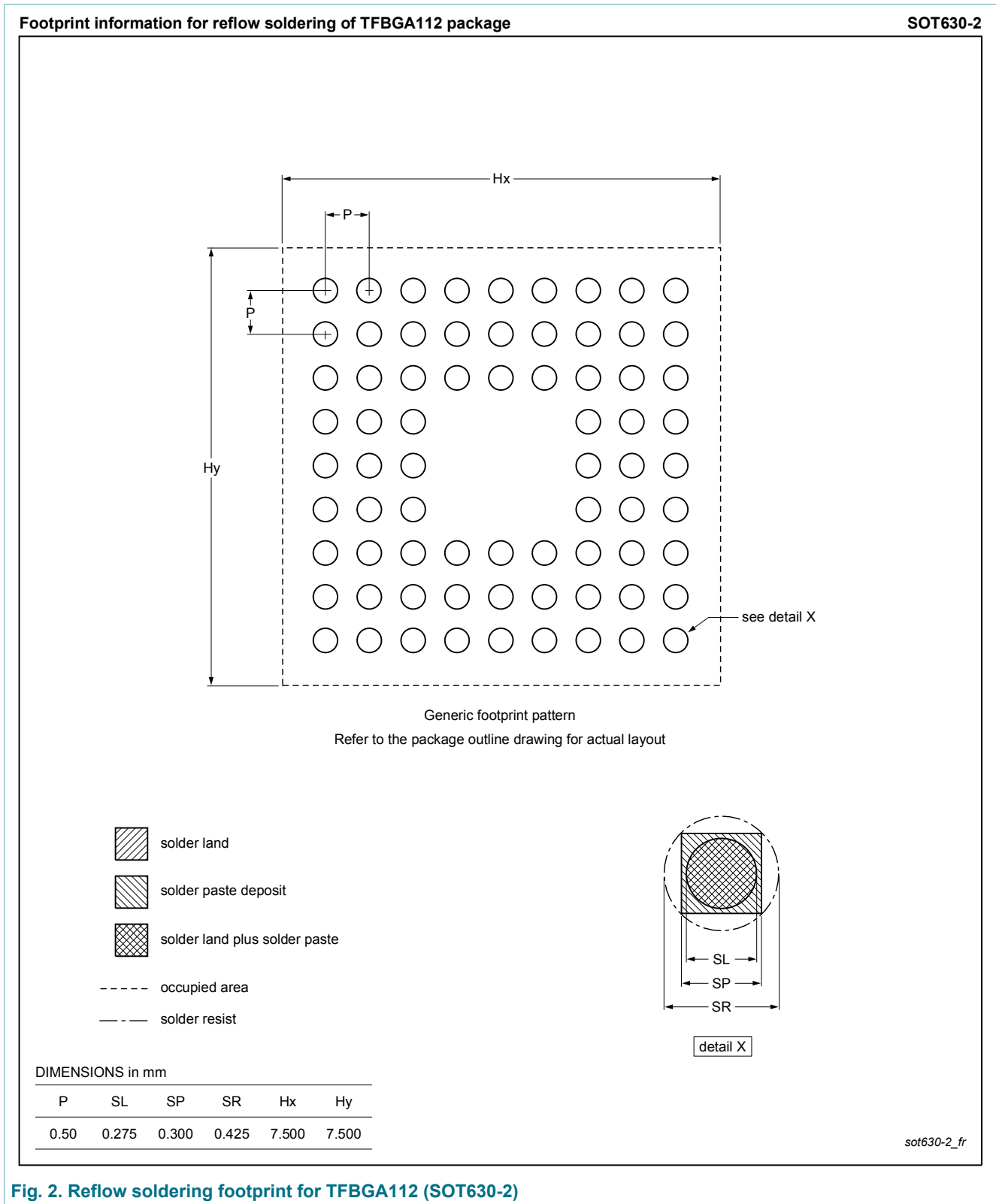


Fig. 2. Reflow soldering footprint for TFBGA112 (SOT630-2)

## 4. Legal information

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